

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A method comprising:

applying a flux on a substrate having solder bumps, the flux including at least a solvent and a water soluble monomer or a water soluble polymer;

placing a die on the substrate; and

reflowing the die in a reflow device at a reflow temperature, the reflow temperature having a temperature profile including an increasing region, an approximately constant region, and a decreasing region, the increasing region including temperature higher than melting point of the polymer and forming polymer liquid ~~to become molten polymer flux~~, the approximately constant region forming solder joints, the decreasing region solidifying the solder joints and the molten polymer flux liquid to re-distribute stress caused by thermal mismatch between the die and the substrate.

2. (original) The method of claim 1 wherein applying the flux comprises:

applying the flux including the water soluble polymer being one of a polyacrylic acid, a polyacrylamide, a polyvinyl alcohol, a starch, and a cellulose.

3. (original) The method of claim 1 wherein applying the flux comprises:

applying the flux including at least an organic solvent and the water soluble monomer.

4. (original) The method of claim 1 wherein applying the flux comprises:

applying the flux including at least an organic solvent and the water soluble polymer.

5. (currently amended) The method of claim 1 wherein reflowing the die comprises:

vaporizing the solvent at an increasing reflow temperature;

melting the polymer into the polymer liquid; and

removing metal oxide from the solder bumps.

6. (currently amended) The method of claim 5 wherein reflowing the die further comprises:

melting the solder bumps;  
forming the solder joints from the melted solder bumps;  
solidifying the solder joints at a decreasing reflow temperature; and  
solidifying the polymer liquid to redistribute the stress.

7. (original) The method of claim 1 wherein reflowing the die comprises:  
vaporizing the solvent at an increasing reflow temperature;  
reacting the monomer to form solid polymer;  
melting the solid polymer into polymer liquid; and  
removing metal oxide from the solder bumps.

8. (previously presented) The method of claim 7 wherein reflowing the die further comprises:

melting the solder bumps;  
forming solder joints from the melted solder bumps;  
solidifying the solder joints at a decreasing reflow temperature; and  
solidifying the polymer liquid.

9. (previously presented) The method of claim 1 further comprising:  
de-fluxing the die to remove polymer residue; and  
dispensing an underfill material into a gap between the die and the substrate.

10. (original) The method of claim 9 wherein de-fluxing comprises:  
dissolving the polymer residue by hot water.

11-30. (canceled)